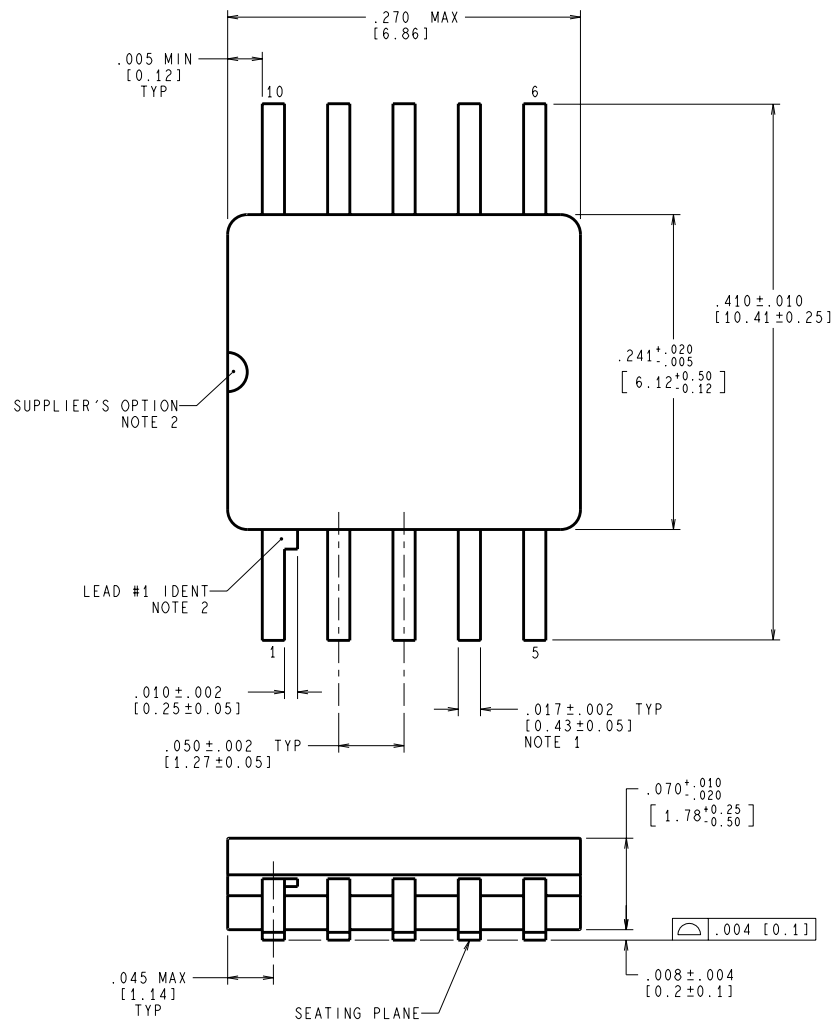


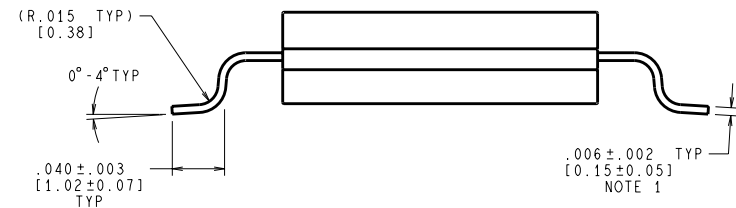


NOTES: UNLESS OTHERWISE SPECIFIED

- LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-PRF-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE. MAXIMUM LIMIT MAY BE INCREASED BY .003 IN/ 0.08mm AFTER LEAD FINISH APPLIED.
- LEAD 1 IDENTIFICATION SHALL BE:
 - A NOTCH OR OTHER MARK WITHIN THIS AREA
 - A TAB ON LEAD 1, EITHER SIDE
- NO JEDEC REGISTRATION AS OF FEBRUARY 1996.

CONTROLLING DIMENSION IS INCH
VALUES IN [] ARE MILLIMETERS

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11374	02/29/1996	MS/KH
B	LD PITCH TOL WAS $\pm .005$; CHANGE LD RADIUS TO REF DIM; REMOVE THE OTHER R. $.006 \pm .002$ DIM $.040 \pm .003$ WAS $.037 \pm .003$	11441	04/19/1996	MS/KH
C	R $.015$ [0.38] WAS R $.006$ [0.15]	11838	10/08/1997	TL/



**MIL-PRF-38535
CONFIGURATION CONTROL**

APPROVALS		DATE		 2900 Semiconductor dr., Santa Clara, CA 95052-8090	
DRAWN: MARTA SUCHY		02/29/96			
DFTG. CHK.					
ENGR. CHK.					
 INCH [MM]				SCALE: N/A SIZE: C DRAWING NUMBER: (SC)MKT-WG10A REV: C	
				DO NOT SCALE DRAWING SHEET 1 of 1	